

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5058	(glass fiber) with (impregnate impregnating impregnated) with (epoxy resin) with (carrer substrate board pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 11:16
L2	817	(semicondcutor chip die dice ic (integrated adj circuit) component) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 11:23
L3	905	(semiconductor chip die dice ic (integrated adj circuit) component) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 11:24
L4	475	(wire wiring) and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:12
L5	1	"5153987".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:01
L6	1	"5235139".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:01
L7	1	"5258094".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:01
L8	1	"5548099".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:01
L9	1	"5843806".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:01
L10	1	"5900676".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:02
L11	1	"5945258".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:02
L12	1	"5948280".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:02
L13	1	"6204559".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:02
L14	1	"5948280".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:02
L15	1	"6238952".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:02

L16	1	"6239384".PN.	USPAT; USOCR	OR	OFF	2005/09/14 10:02
L17	430	3 not 4	US-PPGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:12
L18	425	(glass fiber) with (impregnate impregnating impregnated) with (polyimide polyimide) with (carrier substrate board pcb)	US-PPGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 11:16
L19	78	(semiconducotor chip die dice ic (integrated adj circuit) component) same 18	US-PPGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 11:23
L20	95	(semiconducotor chip die dice ic (integrated adj circuit) component) same 18	US-PPGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 11:24